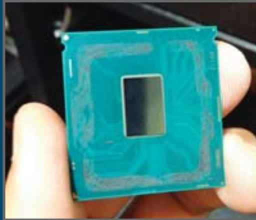
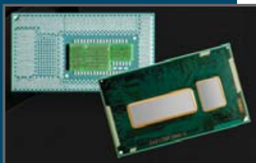
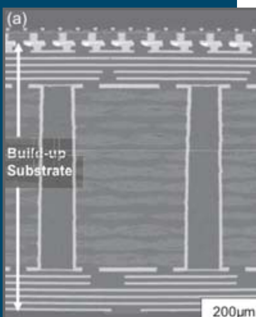
# Advanced Packaging Update:
## *Market and Technology Trends*

*Vol. 2-0819*








This issue of the Advanced Packaging Update presents new developments in advanced packaging substrates, including high-density RDL interposers. Intel's packaging announcements are described. A special section examines mobile phone trends, including a comparison of 5G vs. non-5G phones and packages found in feature phones. TechSearch International's annual survey on substrate design rules is highlighted, with special coverage of suppliers of laminate flip chip BGA and CSP substrates worldwide. The design rules include body size, core thickness, via and pad diameter, minimum bump pitch supported, and substrate finish.

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4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com

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